LY2004

LY2000 series conductive tape is developed with electrically conductive fabric double coated with our new developed bonding conductive acrylic adhesive. This product show excellent conductivity and bonding and widely used in EMI/RFI shielding solutions.

Features

- Easy to convent / die cut
- Applied for EMI/RFI design solution
- Excellent conductivity and bonding
- Upgrade conductive adhesive

Structure

Conductive PSA
Conductive Fabric
Conductive PSA
Liner paper with LYE logo

Specifications

PROPERTIES	DATA	TEST METHOD
Color	Grey	Visual
Total Thickness, mm	0.055	ASTM D1000
Peel Adhesion, kgf/inch	≥ 1.0	PSTC-101
Shear Adhesion, Hour	≥ 48	PSTC-107
Contact Resistance(Z-axial), ohm	< 0.01	MIL-DTL-83528 modified
Service Temperature	-20 to 85	ASTM D1000

 $Total\ thickness\ is\ less\ than\ the\ sum\ of\ thickness\ of\ each\ layer,\ because\ conductive\ adhesive\ is\ permeated\ into\ the\ conductive\ fabric\ backing\ after\ lamination.$

Storage

Storage Temperature: 18~26°C Storage Humidity: 40~60% RH Storage Validity: 6 Months

Regulation

RoHS Compliant & Halogen Free and PFAS-free

APPLICATION TECHNIQUES

Bond strength is dependent upon the amount of adhesive-to-surface contact developed. Firm application pressure and moderate heat, from 100°F (38°C) to 130°F (54°C), will assist the adhesive in developing intimate contact with the bonding surface.

To obtain optimum adhesion, the bonding surfaces must be clean, dry and well unified. Typical cleaning solvents are methyl ethyl ketone for metals or isopropyl alcohol for plastics. Carefully read and follow manufacturer's precautions and directions for use when using cleaning solvents. Ideal tape application temperature range is 70°F to 100°F (21°C to 38°C). Initial tape application to surfaces at temperatures below 50°F (10°C) is not recommended

Disclaimer:

This information is furnished as a guide for selecting materials. LYE disclaims liability for results or use of this information. It is the customer's responsibility to obtain and test samples when determining suitability of material for a particular application.

